# MODEL SOMC Thick Film Resistor Networks

# Dual-in-Line, Small Outline Molded Dip 01, 03, 05 Schematics; 14, 16 or 20 Pins

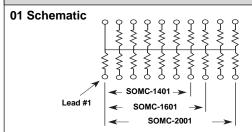




#### **FEATURES**

- .090" [2.29mm] maximum seated height
- · Rugged, molded case construction
- · Highly stable thick film
- .050" [1.27mm] lead spacing
- Low temperature coefficient,
   (- 55°C to + 125°C) ± 100PPM/°C
- Reduces total assembly costs
- Compatible with automatic surface mounting equipment
- Wide resistance range
- Uniform performance characteristics
- Meets EIA PDP100, SOGN-0002 outline dimensions
- Available in tube pack or tape and reel pack

### **CIRCUIT APPLICATIONS**

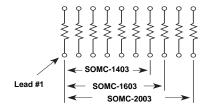


#### 13, 15 or 19 resistors with one pin common

The SOMC-xx01 circuit provides a choice of 13, 15 or 19 nominally equal resistors, each connected between a common pin (14, 16 or 20) and a discrete PC board pin. Commonly used in the following applications:

- MOS/ROM Pull-up/Pull-down
- Open Collector Pull-up
- "Wired OR" Pull-up
- Power Driven Pull-up
- TTL Input Pull-down
- Digital Pulse Squaring
- TTL Unused Gate Pull-up
- High Speed Parallels Pull-up

## 03 Schematic



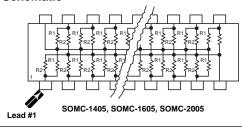
# 7, 8 or 10 isolated resistors

The SOMC-xx03 circuit provides a choice of 7, 8 or 10 nominally equal resistors with each resistor isolated from all others and wired directly across. Commonly used in the following applications:

- "Wired OR" Pull-up
- Power Driven Pull-up
- Powergate Pull-up
- Line Termination

- Long-line Impedance Balancing
- LED Current Limiting
- ECL Output Pull-down
- TTL Input Pull-down

# 05 Schematic



# TTL dual-line terminator;

pulse squaring, 12 or 14 pairs of resistors

(R, Resistors are common to leads 14, 16 or 20)

(R<sub>2</sub> Resistors are common to leads 7, 8 or 10)

The SOMC-xx05 circuit contains 12, 14 or 18 pairs of resistors. Each pair is connected between ground and a common line. The junctions of these resistor pairs are connected to the input leads.

The 05 circuits are designed for TTL dual-line termination and pulse squaring.

#### **ELECTRICAL SPECIFICATIONS**

**Resistance Range:** 10 ohm to 1 Megohm standard. Zero ohm jumpers available.

**Tolerance:** 01 and 03 Schematic =  $\pm$  2% standard.  $\pm$  1%,  $\pm$  5%,  $\pm$  10% and  $\pm$  20% available. 05 Schematic =  $\pm$  2% standard.  $\pm$  5% available. 100 milliohm maximum on zero ohm jumpers.

**Temperature Coefficient:**  $(-55^{\circ}\text{C to} + 125^{\circ}\text{C})$   $\pm 100\text{PPM/}^{\circ}\text{C typical.}$ 

Resistor Power Rating: (Maximum at + 70°C) 01, 05 Schematic = .080 watt.

03 Schematic = .160 watt.

Package Power Rating: (Maximum at + 70°C)

01, 05 Schematic = 14 pin 1.05 watts, 16 pin 1.200 watts, 20 pin 1.520 watts.

03 Schematic = 14 pin 1.125 watts, 16 pin 1.280 watts, 20 pin 1.600 watts.

TC Tracking:  $(-55^{\circ}\text{C to} + 125^{\circ}\text{C}) 50PPM/^{\circ}\text{C}$ .

**Voltage Coefficient of Resistance:** < 50PPM/V typical.

Maximum Operating Voltage: 50 VDC.

**Operating Temperature Range:** - 55°C to + 125°C. **Storage Temperature Range:** - 55°C to + 150°C.

# **MECHANICAL SPECIFICATIONS**

**Marking:** Model number, schematic number, value code, tolerance code.

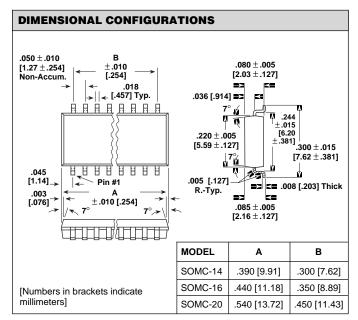
**Marking Resistance to Solvents:** Permanency testing per MIL-STD-202, Method 215.

**Maximum Solder Reflow Temperature:** + 255°C. **Solderability:** Per MIL-STD-202, Method 208E.

Terminals: Copper alloy. 60/40 solder dipped terminal.

**Body:** Molded Epoxy.

### **MODEL SOMC**



ENVIRONMENTAL PERFORMANCE*	
TEST	MAX. ∆R (Typical Test Lots)
Power Conditioning	$\pm$ 0.50% $\Delta$ R
Thermal Shock	$\pm$ 0.50% $\Delta$ R
Short Time Overload	± 0.25% ΔR
Low Temperature Operation	± 0.25% ΔR
Moisture Resistance	± 0.50% ΔR
Resistance to Soldering Heat	± 0.25% ΔR
Shock	± 0.25% ΔR
Vibration	± 0.25% ΔR
Load Life	± 0.50% ΔR
Terminal Strength	± 0.25% ΔR
Insulation Resistance	10,000 Megohm (minimum)
Dielectric Withstanding Voltage	No evidence of arcing or damage (200 V RMS for 1 minute)

<sup>\*</sup> Test methods per MIL-STD-202.

